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** CONTINUING DATA *****

This application is a 371 of PCT/JP04/05004 04/07/2004

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** FOREIGN APPLICATIONS *****

JAPAN 2003103346 04/07/2003
 JAPAN 2003103357 04/07/2003
 JAPAN 2003103435 04/07/2003
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 JAPAN 2003103443 04/07/2003

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Foreign Priority claimed <input checked="" type="checkbox"/> yes <input type="checkbox"/> no	STATE OR COUNTRY JAPAN	SHEETS DRAWING 2	TOTAL CLAIMS 35	INDEPENDENT CLAIMS 5
35 USC 119 (a-d) conditions met <input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after				
Verified and Acknowledged	Examiner's Signature <i>[Signature]</i>	Initials <i>[Initials]</i>		

ADDRESS

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TITLE

Epoxy resin molding material for sealing use and semiconductor device

FILING FEE RECEIVED 5460	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:	<input type="checkbox"/> All Fees
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